## Effective mass



- Effective mass anisotropy
- •Electron effective mass in multivalley semiconductors
- The conductivity effective mass
- The density of states effective mass
- Hole effective mass

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$$\frac{\int_{E(h)^{-}} E(h) - E_{o}}{\int_{h_{o}} E(h)} = \frac{\int_{e} (h_{o}) + \frac{\partial E}{\partial h_{x}^{2}} (h_{x} - h_{x})}{\int_{h_{o}} h} + \frac{\int_{e} \frac{\partial^{2} E}{\partial h_{x}^{2}} (h_{x} - h_{o})^{2} + \frac{\int_{e} 2}{\int_{e} h_{x}^{2}} \frac{\partial^{2} E(h)}{\partial h_{x}^{2}}$$

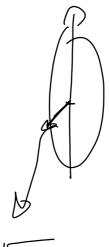
$$\frac{\int_{e} 2^{2} (h_{x} - h_{o})^{2}}{\int_{e} 2^{2} h_{x}^{2}} = \frac{\int_{e} 2^{2} E(h)}{\int_{e} 2^{2} h_{x}^{2}}$$

$$\frac{1}{2}$$
  $\frac{1}{2}$   $\frac{1}$ 

$$2 = \frac{x^2}{\omega^2} + \frac{y^2}{b^2} + \frac{z^2}{c^2}$$

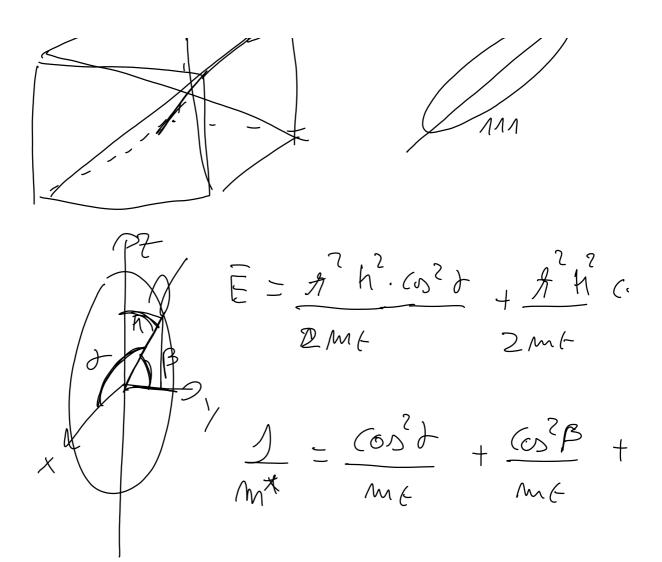
$$1 = \frac{\left(h_{\lambda} - h_{0\lambda}\right)^{2}}{2 m \lambda E} + \frac{\left(h_{\lambda} - h_{0\lambda}\right)^{2}}{2 m y E} + \frac{2 m y E}{4^{2}}$$

$$CQ = \sqrt{\frac{2m_{X}E}{4}} \sqrt{\frac{7}{m_{X}E}}$$









#### Effective mass

The bandstructure around a CB minimum can be expressed as:

$$E(\mathbf{k}) = \frac{\hbar^2 (k_x - k_{x0})^2}{2m_x} + \frac{\hbar^2 (k_y - k_{y0})^2}{2m_y} + \frac{\hbar^2 (k_z - k_{z0})^2}{2m_z}$$

Where  $m_{_{\! X^{\!\scriptscriptstyle \prime}}},\,m_{_{_{\! V^{\!\scriptscriptstyle \prime}}}}$  are the effective masses defined as:

$$\frac{1}{m_x} = \frac{1}{\hbar^2} \frac{\partial^2 E(\vec{k})}{\partial^2 k_x} \qquad \frac{1}{m_y} = \frac{1}{\hbar^2} \frac{\partial^2 E(\vec{k})}{\partial^2 k_y} \qquad \frac{1}{m_z} = \frac{1}{\hbar^2} \frac{\partial^2 E(\vec{k})}{\partial^2 k_z}$$

A high curvature radius in the bandstructure is associated with a "heavy" effective mass and a small curvature radius with a "light" effective mass

$$\frac{1}{\hbar^2}\frac{\partial^2 E\left(\mathbf{k}\right)}{\partial k^2} = \frac{1}{m_k} = \frac{n^2}{m_x} + \frac{l^2}{m_y} + \frac{m^2}{m_z}$$

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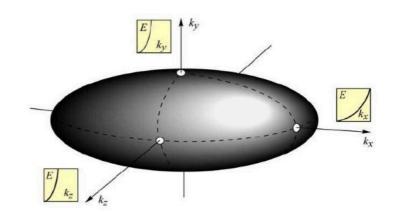
#### Si and Ge conduction band

Che CB of Si and Ge are characterized by two different effective masses named the longitudinal and transverse effective mass  $m_i$  and  $m_t$ . Let's consider the CB minimum placed at  $0.85~\pi/a$  along the [001] direction in the reciprocal space of Si. The longitudinal mass is the one related to transport in the [001] direction, the transverse mass is associated to transport in any direction perpendicular to [001].

$$E(\vec{k}) = E(\vec{k}_0) + \frac{\hbar^2}{2} \left( \frac{k_z^2 + k_y^2}{m_t} + \frac{k_x^2}{m_l} \right)$$

The isoenergetic surface will be an ellipsoid with semiaxes proportional to the square root of  $m_l$  and  $m_t$ .

In the case of Ge  $m_l$  will be along the [111] direction and  $m_t$  along any direction perpendicular to it.

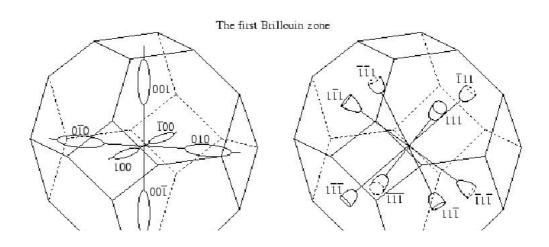


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## Si and Ge conduction band





X valleys of Si



L valleys of Ge

$$m_1 = 0.98 \, m_0$$

$$m_t = 0.19 \, m_0$$

$$m_1 = 1.64 m_0$$

$$m_t = 0.082 \, m_0$$

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## GaAs conduction band

The CB of GaAs features a single minimum at Γ. The isoenergetic surface is, in the parabolic approximation, a sphere with:

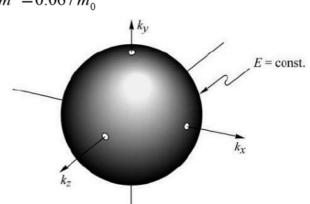
$$E(\vec{k}) = E(0) + \frac{\hbar^2}{2} \left( \frac{k_x^2 + k_y^2 + k_z^2}{m^*} \right)$$

 $m^* = 0.067 m_0$ 

A better approximation is the non-parabolic expression:

$$E(1+\alpha E) = \frac{\hbar^2 k^2}{2 m^*}$$

With  $\alpha = 0.67 \, eV^{-1}$ 



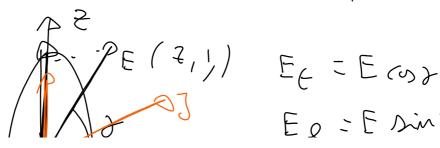
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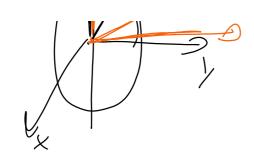
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Effective man tensor - 2 Conductivity

Me V= M= 265

$$M = \frac{965}{\text{m}^{*}}$$





$$M\left(\frac{el}{c_{m^2}}\right)$$

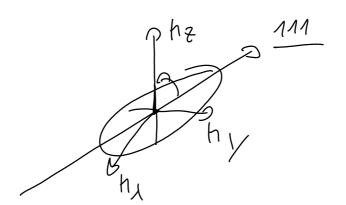
NO PEO

 $3x = \frac{M}{6} 9^2 65 \left(\frac{2}{m_\ell} + \frac{4}{m_\ell}\right) \frac{E_x}{E_x}$ 

$$=\frac{Mg^2\delta_5\left(\frac{1}{m\varrho}+\frac{2}{mL}\right)}{3}E_{\chi}$$

$$31 = \frac{M}{3} g^2 6s \left(\frac{1}{M} + \frac{2}{Mr}\right) = \frac{Ey}{3}$$

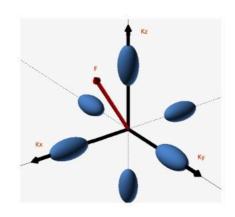
$$\frac{1}{m^{\frac{1}{2}}} = \frac{1}{m^{\frac{1}{2}}} = \frac{1}$$



[211] x51-10

$$\frac{(001)}{\sqrt{3}} = \frac{(001)}{\sqrt{3}}$$

# Conductivity effective mass in Si



$$J_x = q \frac{n}{3} \left( 2 \frac{q\tau}{m_t} + \frac{q\tau}{m_l} \right) F_x,$$

$$J_y = q \frac{n}{3} \left( 2 \frac{q\tau}{m_t} + \frac{q\tau}{m_l} \right) F_y,$$

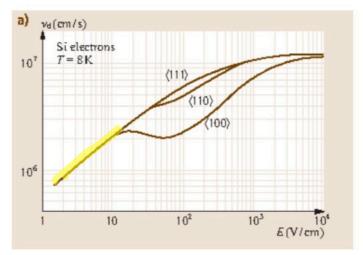
$$J_z = q \frac{n}{3} \left( 2 \frac{q\tau}{m_t} + \frac{q\tau}{m_l} \right) F_z.$$

$$\sigma = q^2 \tau n \, \frac{1}{3} \left( \frac{2}{m_t} + \frac{1}{m_l} \right) \qquad \qquad \frac{1}{m_c} = \frac{1}{3} \left( \frac{2}{m_t} + \frac{1}{m_l} \right)$$

#### Hot-electrons effects in silicon

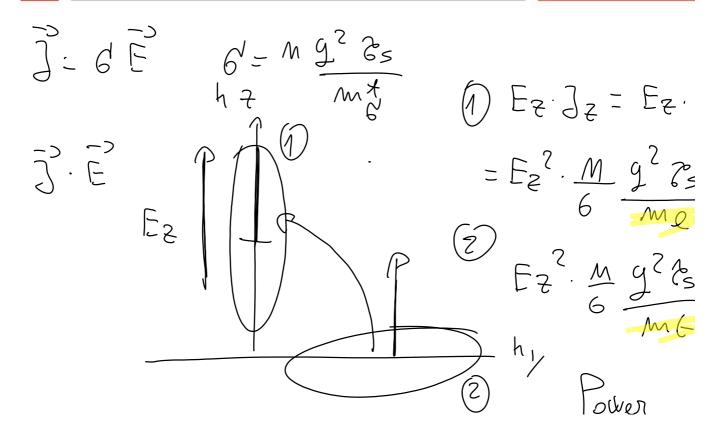
Anisotropic conduction is observed at high electric field E due to valley re-population

when E  $\parallel$  (111) the six valleys are equally oriented with respect to F and all of them give the same contribution to the drift velocity  $v_d$ . When E  $\parallel$  (100), two valleys exhibit the effective mass  $m_l$  in the direction of the field, while the remaining four exhibit the transverse mass  $m_l < m_l$ . Electrons in the transverse valleys respond with a higher mobility, are heated to a greater extent by the field and transfer electrons to the two longitudinal, colder and slower valleys, which results in a lower  $v_d$  than for E  $\parallel$  (111), as seen in the figure



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# Denisty of states and conductivity effective mass

See Appendix A.2 "SemiconductorNanostructures.pdf" (OMPRESSINESTRESSTOOI)

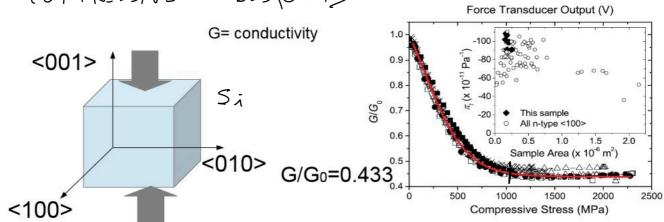


FIG. 2 (color online). (a) Raw data obtained for X parallel to the  $\langle 100 \rangle$  crystal direction in n-type silicon, showing discontinu-

Phys. Rev. Lett. 108, 256801 (2012)

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$$= \frac{m}{g^{2} k_{s}}$$

$$= \frac{m}{g^{2} k_{s}}$$

$$= \frac{m}{m_{e}}$$

$$N_{0} - S_{JOAI}, = M g^{2} k_{s} \frac{1}{3} \left(\frac{2}{m_{e}} + \frac{1}{m_{e}}\right)$$

$$= \frac{m}{3} \frac{g^{2} k_{s}}{m_{e}}$$

$$= \frac{m}$$

# Strained silicon technology-uniaxial strain

# 90 nm Strained Silicon Transistors NMOS PMOS High Stress Film



SiN cap layer Tensile channel strain



SiGe source-drain Compressive channel strain

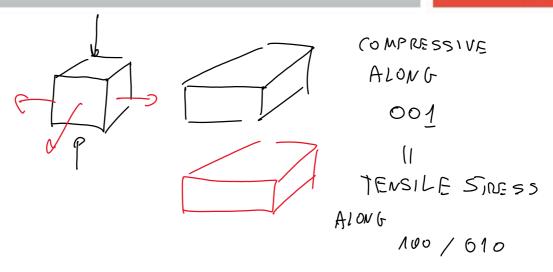
NMOS strain was created by adding a high-stress layer that wrapped around the transistor. PMOS strain was created by replacing the conventional source/drain region with strained SiGe



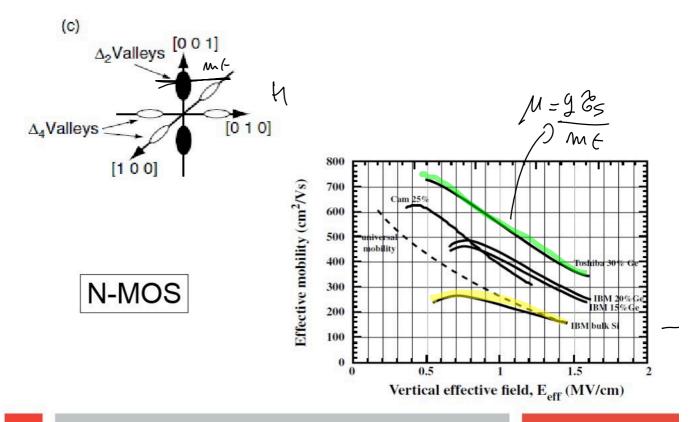
C. Auth, VLSI 2008

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# Strained silicon technology-uniaxial strain



Me, Mf -D Mt,

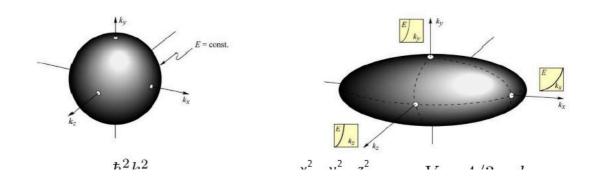
D DOS (3D) = 
$$\frac{12}{11^2 + 3}$$
 ( $\frac{3}{11}$ )  $\frac{1}{12}$ 
 $\frac{1}{12}$   $\frac{1}$ 

DOS = D <u>NUMBER OF STATES</u> D VOLUME Emendy

3

Dos = 
$$\frac{1}{3\sqrt{12}} + 3 \frac{2^{3/2} \sqrt{M_{e} M_{e}^{2}}}{dE}$$
  
Dos =  $\frac{\sqrt{2}}{\sqrt{15}} \sqrt{M_{e} M_{e}^{2}} \sqrt{E} \times M$   
 $\frac{\sqrt{2}}{\sqrt{15}} \frac{3^{3/2}}{\sqrt{15}} \sqrt{E}$   
 $\frac{3^{3/2}}{\sqrt{15}} = M \left( \frac{M_{e} M_{e}^{2}}{\sqrt{15}} \right)^{\frac{1}{2}}$   
 $M_{Dos} = M^{\frac{3}{3}} \sqrt{M_{e} M_{e}^{2}}$ 

# The density of state effective mass



$$E(\mathbf{k}) = \frac{n \kappa}{2m^*}$$

$$DOS = \frac{\sqrt{2}}{\pi^2 \hbar^3} m_{DOS}^{3/2} \sqrt{E}$$

$$\frac{\frac{\lambda}{a^2} + \frac{y}{b^2} + \frac{z}{c^2} = 1}{2m_x E/\hbar^2} + \frac{k_y^2}{2m_y E/\hbar^2} + \frac{k_z^2}{2m_z E/\hbar^2} = 1$$
 
$$\text{DOS= M} \times \frac{\sqrt{2}}{\pi^2 \hbar^3} \sqrt{m_x m_y m_z} \sqrt{E}$$
 
$$m_{DOS} = M^{3/2} \left( m_x m_y m_z \right)^{1/3}$$

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## Denisty of states and conductivity effective mass

Table 0-2. Effective mass and energy bandgap of Ge, Si and GaAs

Name	Symbol	Germanium	Silicon	Gallium Arsenide
Smallest energy bandgap at 300 K	$E_{\rm g}\left({\rm eV}\right)$	0.66	1.12	1.424
Effective mass for density of states calculations				
Electrons	$m_{\rm e}$ , dos/ $m_0$	0.56	1.08	0.067
Holes	$m_{\rm h}$ ,dos/ $m_0$	0.29	$0.57/0.81^{1}$	0.47
Effective mass for conductivity calculations				
Electrons	$m_{\rm e}^*_{,\rm cond}/m_0$	0.12	0.26	0.067
Holes	$m_{\rm h}^*$ ,cond/ $m_0$		0.36/0.386 [7]	0.34

 $m_0 = 9.11 \times 10^{-31} \text{ kg}$  is the free electron rest mass.

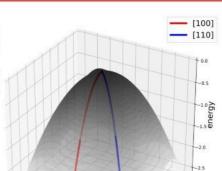
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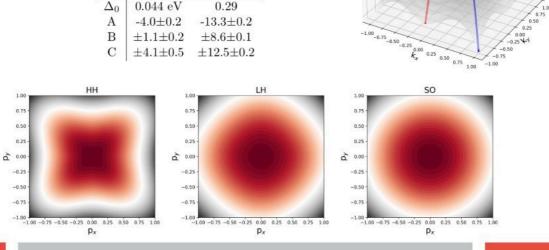
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## Hole effective mass

$$\begin{split} E_{HH} &= -\frac{1}{2m_0} \left( A p^2 + \sqrt{B^2 p^4 + C^2 \left( p_x^2 p_y^2 + p_y^2 p_z^2 + p_z^2 p_x^2 \right)} \right) \\ E_{LH} &= -\frac{1}{2m_0} \left( A p^2 - \sqrt{B^2 p^4 + C^2 \left( p_x^2 p_y^2 + p_y^2 p_z^2 + p_z^2 p_x^2 \right)} \right) \\ E_{SO} &= -\Delta_0 - \frac{1}{2m_0} A p^2, \end{split}$$

Si Ge





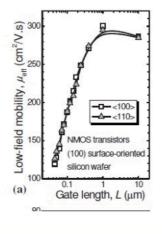
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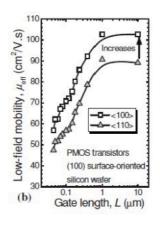
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## Effective mass in n and p MOS

In Si the electron conductivity mass is isotropic i.e. the mobility does not depend on the direction of current flow (see left panel).

On the other hand, the hole effective mass is highly anisotropic. Looking at the isoenergetic contour on the previous slide we notice that the HH effective mass is larger along <110> and smaller along <100>. As a results the hole mobility will be higher along <100> (right panel).





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## Electrons and holes effective mass

Electron effective mass

Hole effective mass

Material el. eff. Bandgap Material Hole eff.

	mass	(eV)	
GaAs	0.063	1.42	
InP	0.077	1.35	
GaSb	0.042	0.72	
InAs	0.023	0.36	
InSb	0.0145	0.17	

Semiconductors for high electron mobility transistors GaAs, InGaAS, InP, InGaP

	mass
Si	0.16 0.49
Ge	0.04 0.28
GaAs	0.076 0.5
InP	0.64
GaSb	0.40
InAs	0.40
InSb	0.40

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